

What is claimed is:

1. An injection moulded product comprising an attached body which has been attached by an intermediate layer, wherein the body has been attached to the injection moulded product by an intermediate layer attached to the body prior to the injection moulding.
2. The product according to the claim 1, wherein the intermediate layer is a thermoplastic adhesive bonding film.
3. The product according to the claim 1, wherein the intermediate layer is an extruded thermoplastic film.
4. The product according to claim 1, 2 or 3, wherein the body is a smart card blank including a circuitry pattern (5) and an integrated circuit on a chip (4).
5. The product according to claim 4, wherein the injection moulded product is a smart card comprising at least one layer (3) formed by injection moulding, the injection mould layer being attached to the smart card blank by the thermoplastic adhesive bonding film.
6. A method for the manufacture of an injection moulded product comprising a body which has been attached by an intermediate layer, wherein the body is attached to the injection moulded product by an intermediate layer adhered to the body prior to the injection moulding.
7. The method according to the claim 6, wherein the intermediate layer is a thermoplastic adhesive bonding film by which the body is attached to the injection moulded product.
8. The method according to the claim 6, wherein the intermediate layer is an extruded thermoplastic film.
9. The method according to claim 8, wherein the body and the intermediate layer attached to the body are placed into an injection

mould and an injection moulding layer is formed on the surface of the intermediate layer.

5 10. A smart card blank comprising a substrate including a circuitry pattern and an integrated circuit on a chip, and to at least one side of the substrate has been attached an intermediate layer, wherein the intermediate layer is a thermoplastic adhesive bonding film.

10 11. A smart card blank according to claim 10, wherein the thermoplastic adhesive bonding film is a polyurethane based film, or a film based on modified polyolefin.

15 12. A smart card blank web comprising a carrier web including successive and/or parallel circuitry patterns, which are each equipped with an integrated circuit on a chip, and at least one side of the substrate has been attached an intermediate layer in a web form, wherein the intermediate layer is a thermoplastic adhesive bonding film.

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